

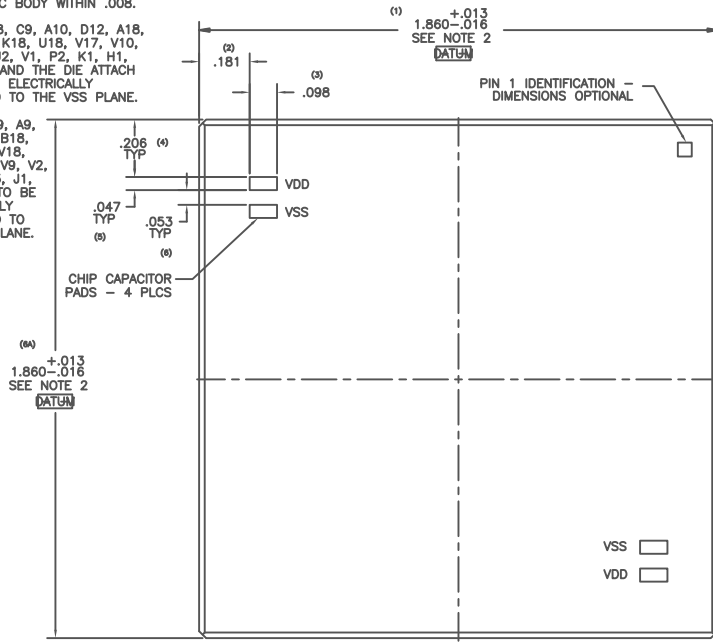
SSM P/N CPG22307

1. THIS PART TO BE MANUFACTURED PER THE LATEST REVISION SPECIFICATION TITLED, "PIN GRID ATTRIBUTE SPECIFICATION."

2. ALL CAVITIES MUST BE CENTERED ON CERAMIC BODY WITHIN .008.

3. PINS B2, A8, C9, A10, D12, A18, B17, H17, K18, U18, V17, V10, U11, V8, U2, V1, P2, K1, H1, H3, & E3 AND THE DIE ATTACH PAD TO BE ELECTRICALLY CONNECTED TO THE VSS PLANE.

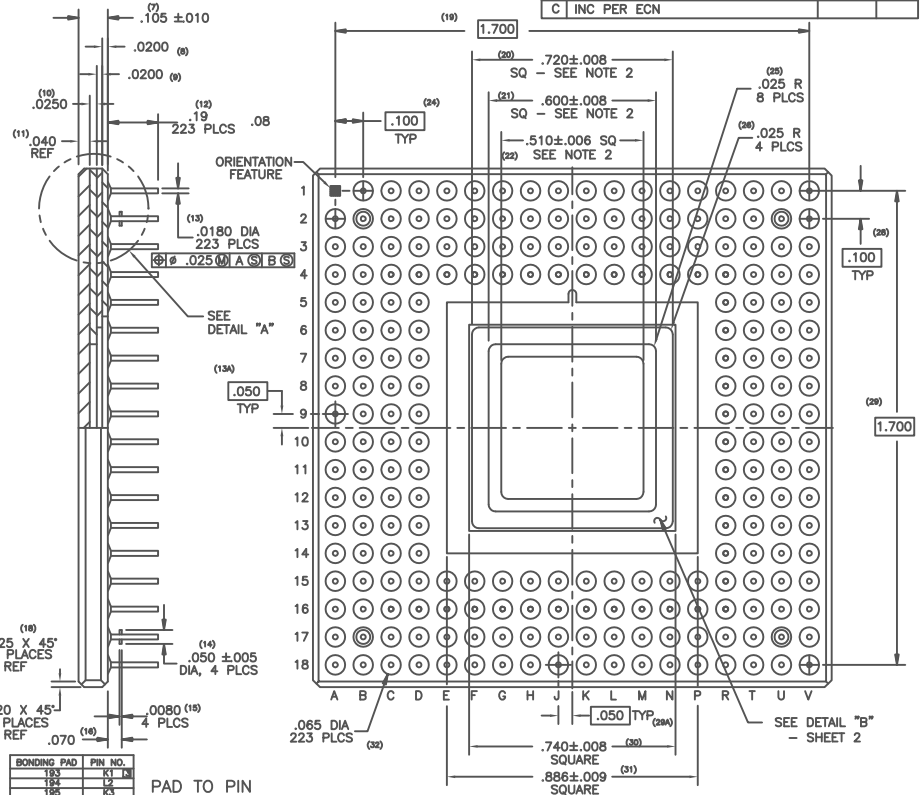
4. PINS A2, B9, A9, B13, A17, B18, J18, L18, V18, U17, V12, V9, V2, U1, N4, L3, J1, G1 & B1 TO BE ELECTRICALLY CONNECTED TO THE VDD PLANE.



(6A) +.013
1.860 ± .016
SEE NOTE 2
DATUM

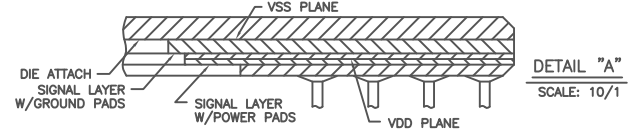
VSS □
VDD □

BONDING PAD	PIN NO.	BONDING PAD	PIN NO.	BONDING PAD	PIN NO.	BONDING PAD	PIN NO.	BONDING PAD	PIN NO.	BONDING PAD	PIN NO.	BONDING PAD	PIN NO.	BONDING PAD	PIN NO.
1	B2 [N]	33	D10	65	D17	97	M17	129	V10 [N]	161	V6	193	K1 [N]	225	B1 [N]
2	D4	34	A12	66	D18	98	N18	130	V14	162	U6	194	L4	226	D1
3	B3	35	E11	67	F15	99	N19	131	E5	163	V4	195	F4	227	D2
4	B5	36	B12	68	F16	100	N15	132	U13	164	R5	196	J1 [N]	228	D3
5	A3	37	D11	69	E16	101	N17	133	T11	165	V5	197	H1 [N]	229	D4
6	D5	38	A9 [N]	70	G15	102	P17	134	V13	166	V2 [N]	198	L1	230	D5
7	B4	39	A10 [N]	71	E17	103	P18	135	K10	167	U2 [N]	199	K2	231	D6
8	D4	40	A10 [N]	72	E16	104	R18	136	U12	168	U1 [N]	200	J5	232	D7
9	A4	41	G12	73	E18	105	P16	137	F10	169	V1 [N]	201	J5	233	D8
10	D4	42	B13 [N]	74	H15	106	P15	138	V12 [N]	170	U5	202	L2	234	D9
11	D6	43	D12 [N]	75	F17	107	R17	139	U11 [N]	171	R4	203	J4	235	D10
12	B5	44	A14	76	H18	108	H18	140	V11	172	T3	204	G1 [N]	236	D11
13	D6	45	G13 [N]	77	F18	109	R16	141	R9	173	V2	205	H5 [N]	237	D12
14	D4 [N]	46	B14	78	J15	110	T17	142	U10	174	T1	206	G2	238	D13
15	D4 [N]	47	G14	79	G17	111	U18 [N]	143	R9	175	R1	207	G2	239	D14
16	D5	48	G13 [N]	80	J16	112	V18 [N]	144	D9	176	R3	208	F1	240	D15
17	D7	49	A15	81	G18	113	V17 [N]	145	R8	177	R2	209	G3	241	D16
18	B6	50	B15 [N]	82	J16 [N]	114	R15	146	U6	178	R1	210	F4	242	D17
19	D7	51	G14	83	H17 [N]	115	T16	147	R6	179	P3	211	G4	243	D18
20	D6	52	G15	84	L18 [N]	116	U16	148	V7	180	H4 [N]	212	F3	244	D19
21	D6	53	A16	85	K18 [N]	117	V16	149	V7	181	P4 [N]	213	F3	245	D20
22	B7	54	A17 [N]	86	K18	118	R14	150	U7	182	N5	214	E3	246	D21
23	D2	55	B17 [N]	87	F19	119	T15	151	R7	183	P1	215	E3 [N]	247	D22
24	A7	56	B18 [N]	88	K15	120	U15	152	V8 [N]	184	M4	216	F4	248	D23
25	D9	57	E17 [N]	89	J17	121	V15	153	V8 [N]	185	N5	217	D1	249	D24
26	D9	58	B18 [N]	90	L16	122	R13	154	V8 [N]	186	M5	218	D2	250	D25
27	D9 [N]	59	D15	91	K17	123	T13	155	T6	187	N1	219	D3	251	D26
28	D9 [N]	60	G16	92	L15	124	T14	156	U6	188	L4	220	E4	252	D27
29	B10	61	G17	93	L17	125	R12	157	R8	189	M2	221	C1	253	D28
30	A11	62	G18	94	M18	126	U14	158	V5	190	L2 [N]	222	C2	254	D29
31	C10	63	G19	95	R19	127	T12	159	V5	191	H1	223	C3	255	D30
32	B11	64	D18	96	M15	128	U17 [N]	160	T5	192	K4	224	B1 [N]	256	D31



PAD TO PIN TABLE

☒ = SEE NOTE 3
☑ = SEE NOTE 4



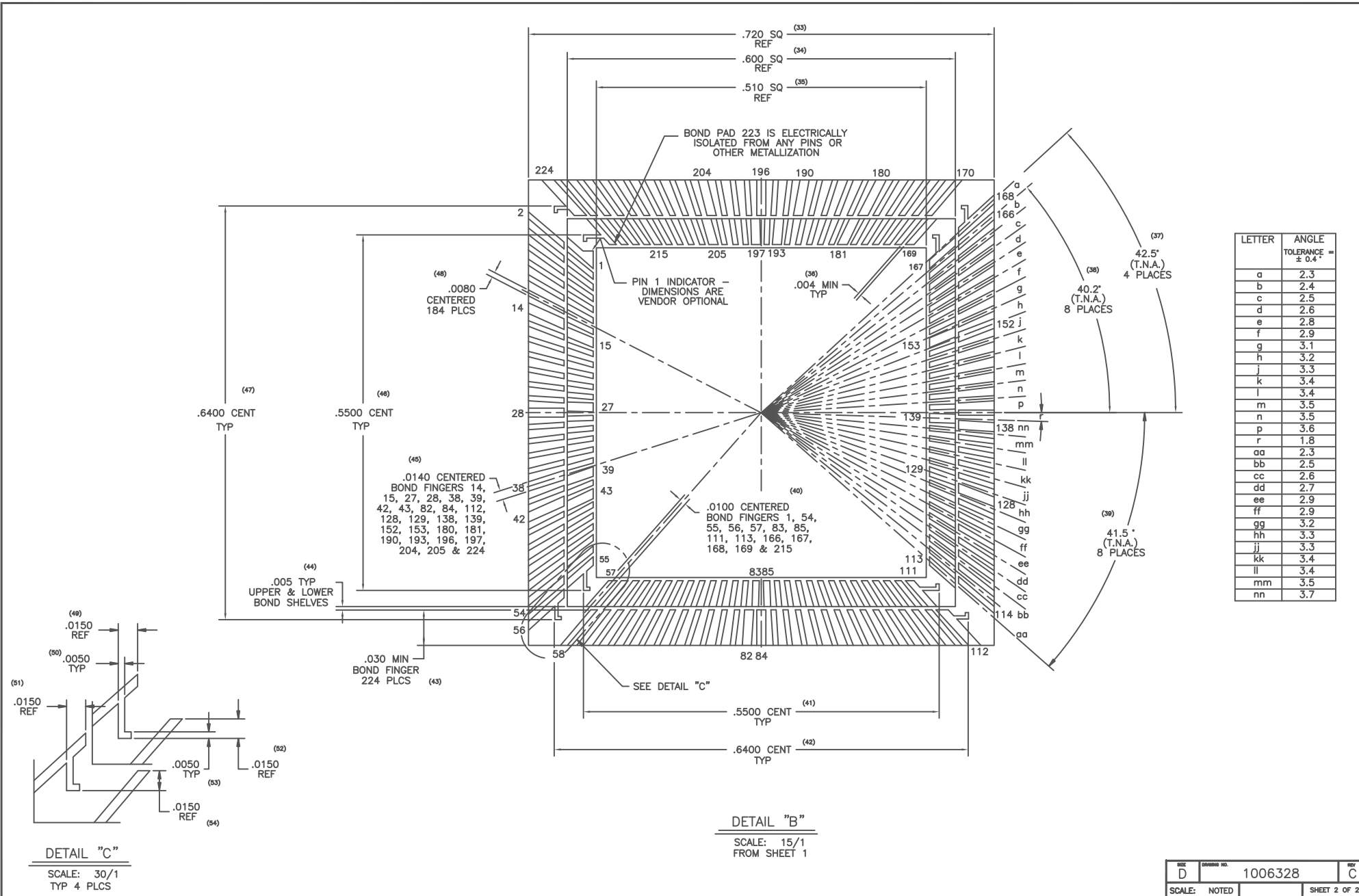
REVISIONS			
LTR	DESCRIPTION	APPROVED	DATE
A	.800 SQ CHM. WAS .860 SQ CHM.; .860/.750 RESIN DAM WAS .690/.850; ADDED .080 DIA WASS. 072 WAS .260; .157 WAS .160; .0160 WAS .0275; .0270 WAS .0230; .045 REF WAS .0446 REF; .062 SQ CHM. O.A. WAS .072 BOWDICE; 1 & 2; REVISED NOTES; COMPLETED PAD-PIN TABLE	JR	3-18-89
B	1.88 SQUARE (±.01) WAS 1.860 ±.020; ELIMINATED CHIP CAPACITOR PADS; SHT. 2 - .030 MIN BOND PING WAS .040	JR	4-12-89

1006328
223 PIN, CERAMIC PIN
GRID ARRAY, CAVITY DOWN
SHEET 1 OF 2



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SSM P/N CPG22307



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SIZE D	DRAWING NO. 1006328	REV C
SCALE: NOTED		SHEET 2 OF 2